

## **Application Data Sheet**

### **Application Information**

Application Type::	Regular
Subject Matter::	Utility
Suggested classification::	
Suggested Group Art Unit::	
CD-ROM or CD-R?::	None
Title::	Apparatus and process for precise encapsulation of flip chip interconnects
Attorney Docket Number::	CPAC 1011-2 US
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	
Total Drawing Sheets::	
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

### **Applicant Information**

Applicant Authority Type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Rajendra
Family Name::	PENDSE
City of Residence::	Fremont
State or Province of Residence::	CA
Country of Residence::	US
Street of mailing address::	5245 Diamond Common
City of mailing address::	Fremont
State or Province of mailing address::	CA
Country of mailing address::	US

Postal or Zip Code of mailing address:: 94555

## Correspondence Information

Correspondence Customer Number:: 22470

## Representative Information

Representative Customer Number::	22470	
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## Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non-Provisional of	60/272,280	02/27/01

## Assignee Information

Assignee name:: ChipPAC, Inc.  
Street of mailing address:: 47400 Kato Road  
City of mailing address:: Fremont  
State or Province of mailing address:: CA  
Country of mailing address:: US  
Postal or Zip Code of mailing address:: 94538